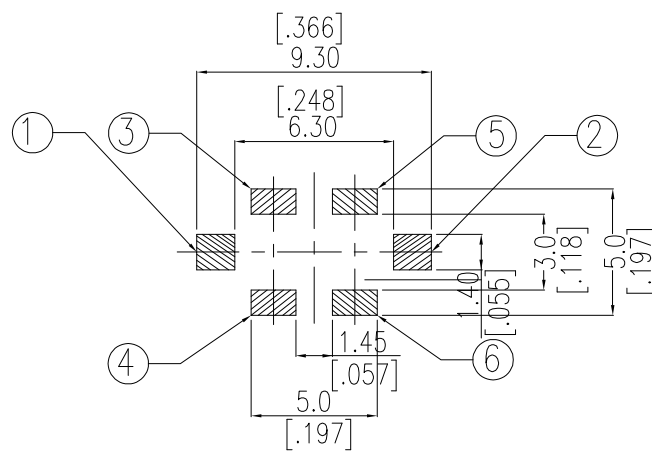
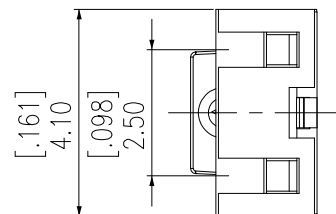
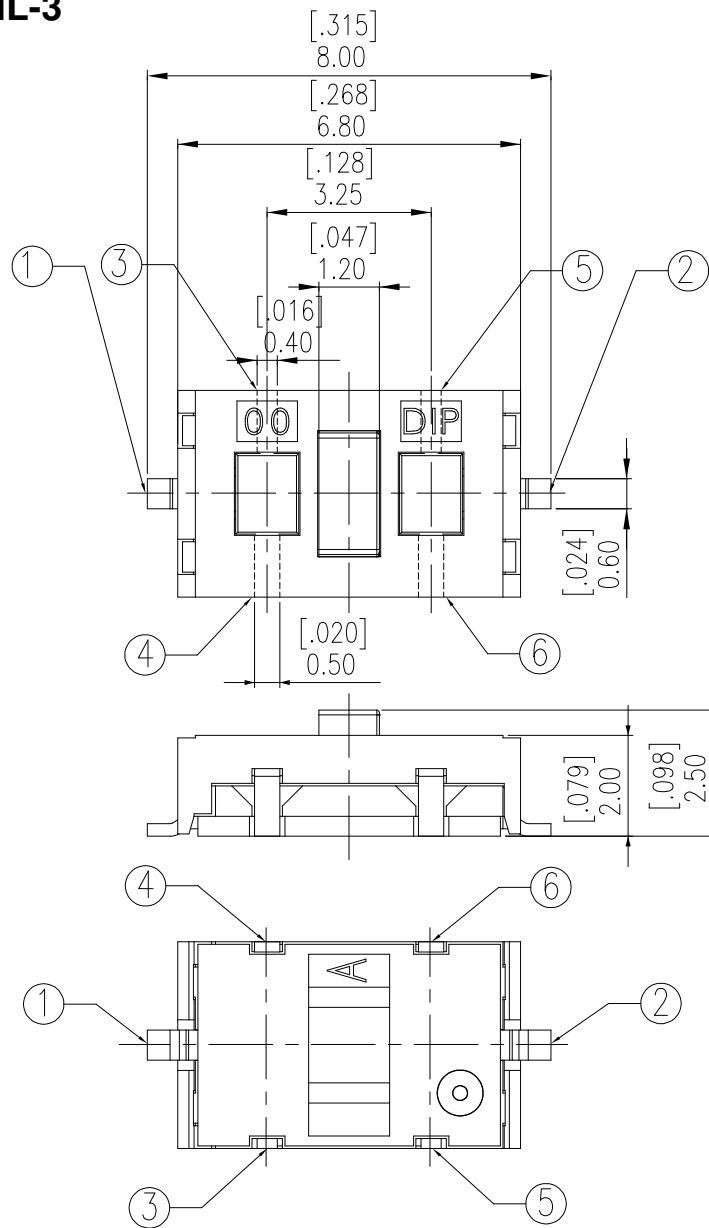


TML-3 SERIES

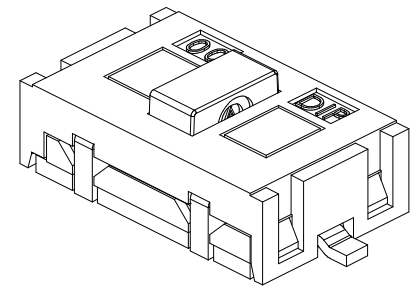


DIMENSIONS

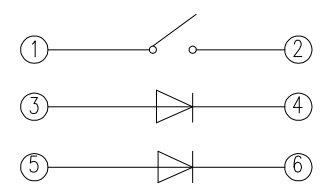
TML-3



P.C.B. LAYOUT



NO.	LED COLOR
X	NON-LED
R	RED
O	SOFT ORANGE
G	GREEN
B	BLUE
A	AMBER
B5	BLUE(LED 5mA)



CIRCUIT DIAGRAM

General Tolerance : $\pm 0.2\text{mm}$

HOW TO ORDER

T M L - 3 W ☐ ☐ - ☐ - ☐

Package Style :
T/R = Tape & Reel

Soldering :
V = Lead Free Solderable

Right LED Color
X = No LED
R = Red
G = Greed
O = Soft Orange
B = Blue
A = Amber
B5=Blue(LED 5mA)

Left LED Color
X = No LED
R = Red
G = Green
O = Soft Orange
B = Blue
A = Amber
B5=Blue(LED 5mA)

Operating Force :
W = White, 160gf

Prod. No.
4.1X6.8mm

Tactile Switch

SPECIFICATION

△MECHANICAL

Operation Force: 160±50gf Brown (N)
Stroke : 0.25+0.2/-0.1mm
Operation Temperature: -20℃ to +70℃
Storage Temperature: -30℃ to +80℃

△ELECTRICAL

Electrical Life: 50,000 cycles for 160gf
Rating:50mA , 12VDC
Contact Resistance: 100mΩ max.
Insulation Resistance: 100MΩ min. 500V DC
Dielectric Strength: 250VAC / 1 minute
Contact Arrangement 1 pole 1 throw
LED : See Specification.

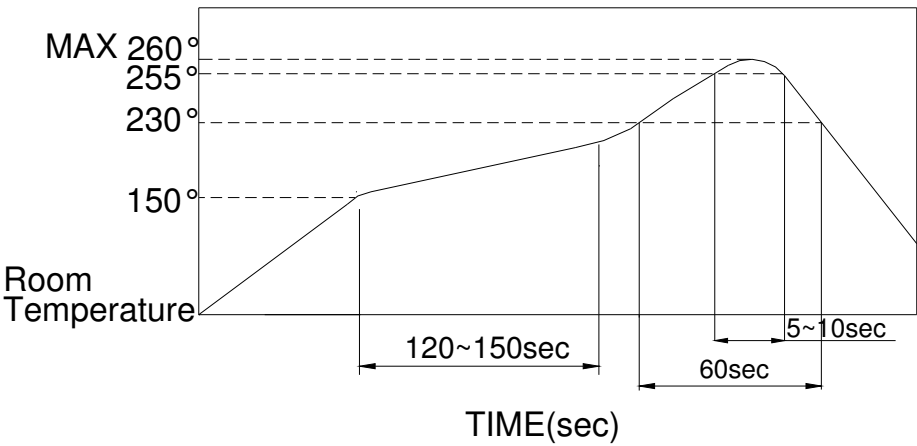
MATERIAL

△Cover : UL 94V-0 Nylon High-temp Thermoplastic.
Color : White
△STEM : UL 94V-0 Nylon High-temp Thermoplastic.
Color : Black
△CONTACT : Stainless with silver cladding.
△BASE : UL 94V-0 Nylon High-temp Thermoplastic.
Color : White(160gf)
△TERMINAL : Brass, Silver cladding
△ADHESIONS TAPE : Kapton

SOLDERING PROCESS

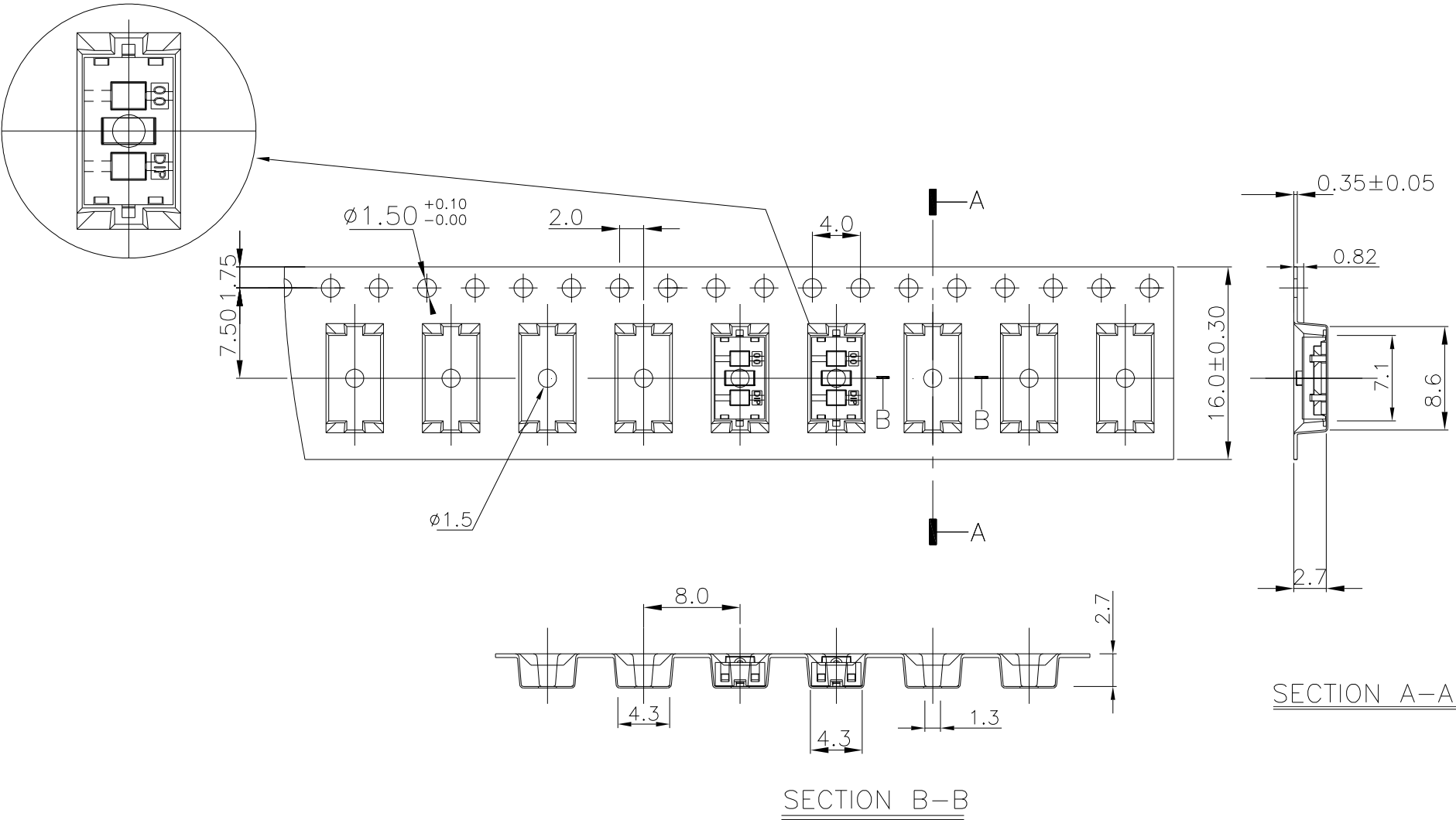
△HAND SOLDERING: Use a soldering iron of 30 watts, controlled at 350℃ approximately Max 5 seconds while applying.
△REFLOW SOLDERING: When applying reflow soldering, the peak temperature or the reflow oven should be set to 260℃ max.
△CONDITION FOR SOLDERING : Reflow & non-washable type

△Temperature Profile :



PACKING

Part Number	Number Per Reel	Number Per Bag
TML-3	3000	-



General Tolerance : ±0.1mm

PRECAUTION in HANDLING

△After reflow, do not touch LED before cooling, or it could influence LED function.
△It is a normal material characteristic when yellowing on plastic surface after reflow.
△Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch